

TF-3050G

SERIES 2 BL8S THIN FILM CHIP TRIMMER



A New Generation Platform for Trim and Test Thin Film Chip Components

- Capability to trim from ohms (Ω) to Mega-ohms ($M\Omega$)
- Ability to trim substrates with resistors up to size 0.04"X0.02"
- Substrate size available for 50mmX60mm,60mmX70mm
- Theta adjustment for clamping device for precise alignment
- Twin magazines to store additional substrates and reduce machine idle time.

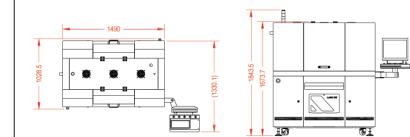
TF-3050G SERIES 2 BL8S THIN FILM CHIP TRIMMER SPECIFICATIONS

Optical System

- Beam Positioned: Precision high-speed galvanometer
- Field Size: 12 x 75mm
- Resolution: 1.5 μ m
- Repeatability: 2.5 μ m
- Spot Size: 8-10 μ m (standard 532nm)
- Focus Len: 102 mm flat telecentric type

Physical Characteristics

- Dimensions: 1490mm x 1028mm x 1843.5mm



Laser System

- Laser Type: Diode pumped Q-switched
- Output Power: 1.5W (Average @ 20 KHz)
- Wavelength: Standard 532nm
- Model: TEM₀₀
- Frequency Range: 1-100KHz
- Pulse width, nominal: 7 nsec
- Power Measurement: Thermal pickup

X/Y Part Positioning

- Type: Dual carriage mounted on independent air cooled brushless DC servo motor stages
- X Axis: Driven by high speed linear motor (carriages) - XY Resolution: 1 μ m
- Travel Speed: 600 mm/s
- Prober: High speed linear motor with pneumatic counter balance and motorized theta
- Theta Control: Motorized theta control
- Part Transfer: Pneumatically controlled pick and place arms
- Part Load/Unload: Dual magazines with elevators

Measurement System

- Dual Mode: Force Current & Force Voltage
- Range: 0.1 Ω ~ 30 $M\Omega$, 10 m Ω Optional
- Accuracy: 0.02% Midrange
- Repeatability: 0.01% Midrange
- Resolution: 0.005%
- Measurement Time: 50 μ sec
- Calibration Standards: 6 pcs 0.01%
- Guard Drive Current: 100 mA
- Guard Offset: 1 mV

Utilities Requirements

- Power: 220 VAC, single phase, 10A (50/60Hz)
- Air: 80~100 psi / flow rate 10 cfm
- Vacuum: 100 CFM factory vacuum for debris removal and substrates retention

Controller

- Pentium processor for trimmer application and motion control

Special Features

- Dual magazine with two sets of magazines to reduce the machine idle time
- Improved pick up arm for efficient pick up and placing of substrates

Software

- DOS Application Software

Switching Matrix

- Pins per Card: 16
- Lines per Pin: 3 (Force, Sense or Guard)
- Cards per System (Standard): 10 pcs std, 12 pcs maximum
- Switch Type: Dry Reed Relay
- Contact Life: 1 Billion Cycles
- Insulation: > 10 G Ω
- Switching Time: 200 μ sec

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